[MOSFET](#) – SiC Power, Single N-Channel, D2PAK-7L

900 V, 20 mΩ, 112 A

NVBG020N090SC1

Features

- Typ. $R_{DS(on)}$ = 20 mΩ @ V_{GS} = 15 V
- Typ. $R_{DS(on)}$ = 16 mΩ @ V_{GS} = 18 V
- Ultra Low Gate Charge (typ. $Q_{G(tot)}$ = 200 nC)
- Low Effective Output Capacitance (typ. C_{oss} = 295 pF)
- 100% Avalanche Tested
- Qualified According to AEC−Q101
- RoHS Compliant

Typical Applications

- Automotive On Board Charger
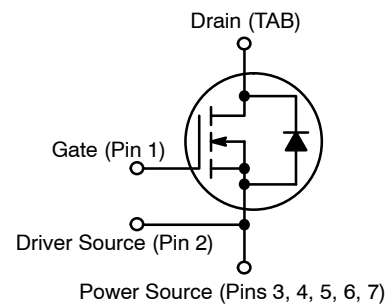- Automotive DC/DC Converter for EV/HEV

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

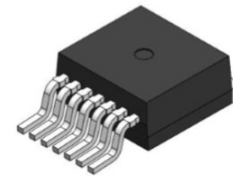| Parameter			Symbol	Value	Unit
Drain−to−Source Voltage			V_{DSS}	900	V
Gate−to−Source Voltage			V_{GS}	+22/−8	V
Recommended Operation Values of Gate – Source Voltage		T_C < 175°C	V_{GSop}	+15/−5	V
Continuous Drain Current $R_{θJC}$ (Note 2)	Steady State	T_C = 25°C	I_D	112	A
Power Dissipation $R_{θJC}$ (Note 2)			P_D	477	W
Continuous Drain Current $R_{θJA}$ (Notes 1, 2)	Steady State	T_A = 25°C	I_D	9.8	A
Power Dissipation $R_{θJA}$ (Notes 1, 2)			P_D	3.7	W
Pulsed Drain Current (Note 3)		T_A = 25°C	I_{DM}	448	A
Single Pulse Surge Drain Current Capability (Note 4)	T_A = 25°C, t_p = 10 μs, R_G = 4.7 Ω		I_{DSC}	854	A
Operating Junction and Storage Temperature Range			T_J, T_{stg}	−55 to +175	°C
Source Current (Body Diode)			I_S	148	A
Single Pulse Drain−to−Source Avalanche Energy (I_L = 23 A_{pk}, L = 1 mH) (Note 5)			E_{AS}	264	mJ
Maximum Lead Temperature for Soldering, 1/8″ from Case for 10 Seconds			T_L	245	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Surface mounted on a FR−4 board using 1 in2 pad of 2 oz copper.
2. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
3. Repetitive rating, limited by max junction temperature.
4. Peak current might be limited by transconductance.
5. E_{AS} of 264 mJ is based on starting T_J = 25°C; L = 1 mH, I_{AS} = 23 A, V_{DD} = 100 V, V_{GS} = 15 V.

ON Semiconductor®

$V_{(BR)DSS}$	$R_{DS(ON)}$ MAX	I_D MAX
900 V	28 mΩ @ 15 V	112 A

Drain (TAB)
Gate (Pin 1)
Driver Source (Pin 2)
Power Source (Pins 3, 4, 5, 6, 7)

N−CHANNEL MOSFET

D2PAK−7L
CASE 418BJ

MARKING DIAGRAM

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AYWWZZ
NVBG
020N090SC1
o
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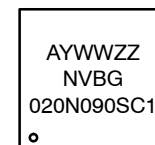
A = Assembly Location
Y = Year
WW = Work Week
ZZ = Lot Traceability
NVBG020N090SC1 = Specific Device Code

ORDERING INFORMATION

Table 1. THERMAL CHARACTERISTICS

Parameter	Symbol	Max	Units
Thermal Resistance Junction–to–Case (Note 2)	$R_{\theta JC}$	0.31	°C/W
Thermal Resistance Junction–to–Ambient (Notes 1, 2)	$R_{\theta JA}$	41	°C/W

Table 2. ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise stated)

Parameter	Symbol	Test Condition		Min	Typ	Max	Unit
OFF CHARACTERISTICS							
Drain–to–Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0 V, I_D = 1 mA		900			V
Drain–to–Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	I_D = 1 mA, refer to 25°C			440		mV/°C
Zero Gate Voltage Drain Current	I_{DSS}	V_{GS} = 0 V V_{DS} = 900 V	T_J = 25°C			100	μA
			T_J = 175°C			250	μA
Gate–to–Source Leakage Current	I_{GSS}	V_{GS} = +22/–8 V, V_{DS} = 0 V				±1	μA
ON CHARACTERISTICS							
Gate Threshold Voltage	$V_{GS(TH)}$	V_{GS} = V_{DS} , I_D = 20 mA		1.8	2.6	4.3	V
Recommended Gate Voltage	V_{GOP}			–5		+15	V
Drain–to–Source On Resistance	$R_{DS(on)}$	V_{GS} = 15 V, I_D = 60 A, T_J = 25°C			20	28	mΩ
		V_{GS} = 18 V, I_D = 60 A, T_J = 25°C			16		
		V_{GS} = 15 V, I_D = 60 A, T_J = 175°C			27		
Forward Transconductance	g_{FS}	V_{DS} = 20 V, I_D = 60 A			49		S
CHARGES, CAPACITANCES & GATE RESISTANCE							
Input Capacitance	C_{ISS}	V_{GS} = 0 V, f = 1 MHz, V_{DS} = 450 V			4415		pF
Output Capacitance	C_{OSS}				295		
Reverse Transfer Capacitance	C_{RSS}				25		
Total Gate Charge	$Q_{G(TOT)}$	V_{GS} = –5/15 V, V_{DS} = 720 V, I_D = 60 A			200		nC
Threshold Gate Charge	$Q_{G(TH)}$				42		
Gate–to–Source Charge	Q_{GS}				76		
Gate–to–Drain Charge	Q_{GD}				56		
Gate–Resistance	R_G	f = 1 MHz			1.5		Ω
SWITCHING CHARACTERISTICS							
Turn–On Delay Time	$t_{d(ON)}$	V_{GS} = –5/15 V, V_{DS} = 720 V, I_D = 60 A, R_G = 2.5 Ω, Inductive Load			39		ns
Rise Time	t_r				52		
Turn–Off Delay Time	$t_{d(OFF)}$				58		
Fall Time	t_f				13		
Turn–On Switching Loss	E_{ON}				1551		μJ
Turn–Off Switching Loss	E_{OFF}				179		
Total Switching Loss	E_{TOT}				1730		
DRAIN–SOURCE DIODE CHARACTERISTICS							
Continuous Drain–Source Diode Forward Current	I_{SD}	V_{GS} = –5 V, T_J = 25°C				148	A
Pulsed Drain–Source Diode Forward Current (Note 3)	I_{SDM}	V_{GS} = –5 V, T_J = 25°C				448	A
Forward Diode Voltage	V_{SD}	V_{GS} = –5 V, I_{SD} = 30 A, T_J = 25°C			3.7		V

NVBG020N090SC1

Table 2. ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise stated)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
DRAIN−SOURCE DIODE CHARACTERISTICS						
Reverse Recovery Time	t_{RR}	V_{GS} = −5/15 V, I_{SD} = 60 A, dI_S/dt = 1000 A/μs, V_{DS} = 720 V		28		ns
Reverse Recovery Charge	Q_{RR}			186		nC
Reverse Recovery Energy	E_{REC}			4		μJ
Peak Reverse Recovery Current	I_{RRM}			14		A
Charge time	Ta			17		ns
Discharge time	Tb			11		ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS
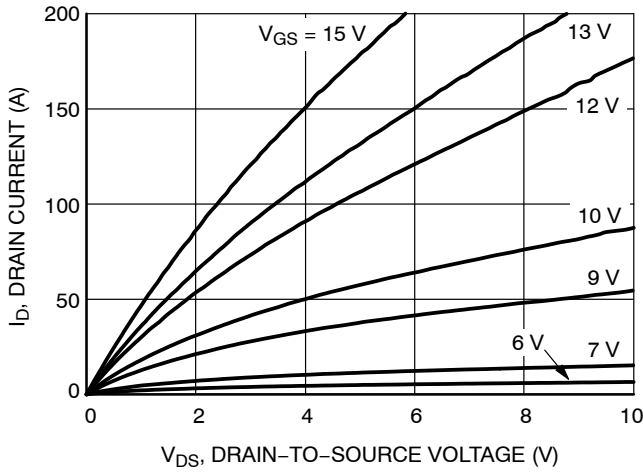
Figure 1. On−Region Characteristics
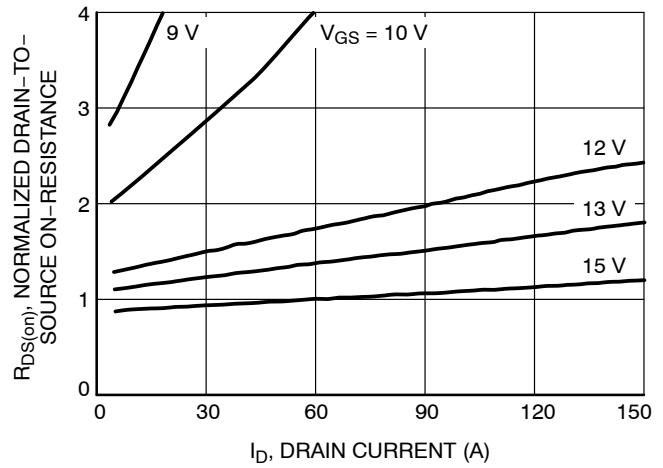
Figure 2. Normalized On−Resistance vs. Drain Current and Gate Voltage
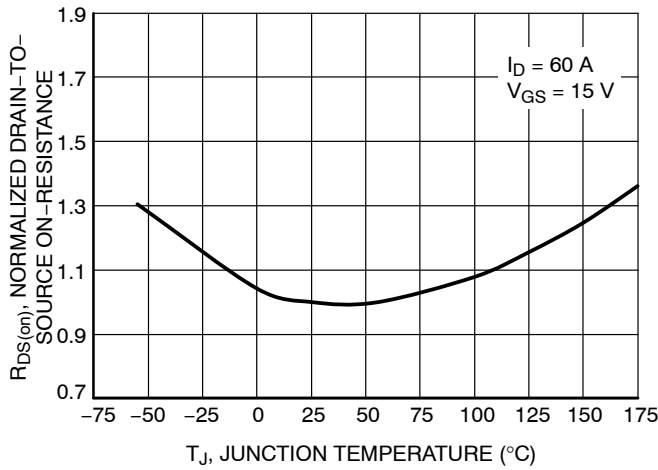
Figure 3. On−Resistance Variation with Temperature
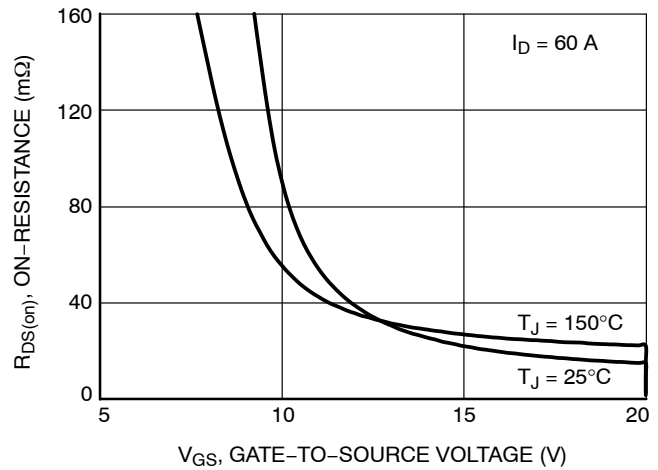
Figure 4. On−Resistance vs. Gate−to−Source Voltage
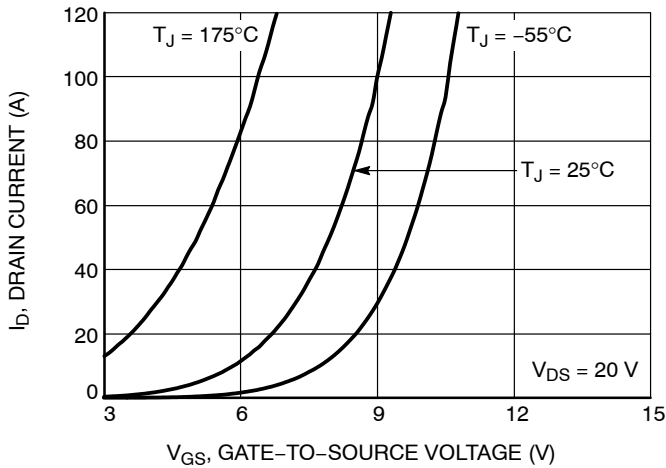
Figure 5. Transfer Characteristics
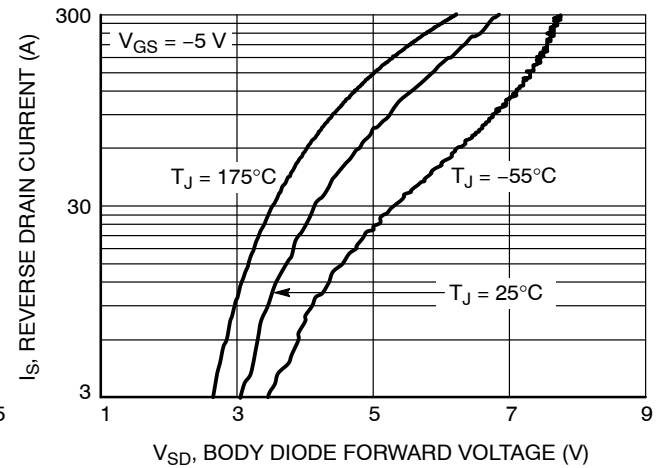
Figure 6. Diode Forward Voltage vs. Current

TYPICAL CHARACTERISTICS
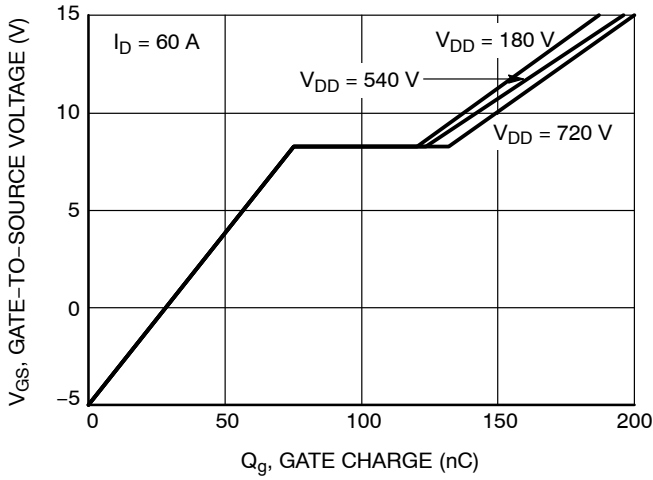
Figure 7. Gate–to–Source Voltage vs. Total Charge
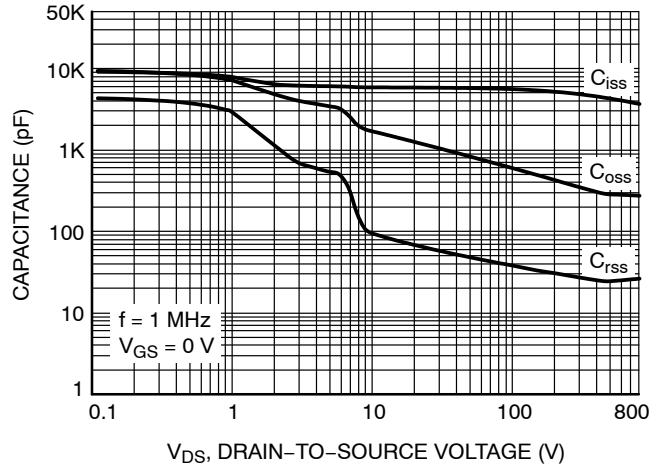
Figure 8. Capacitance vs. Drain–to–Source Voltage
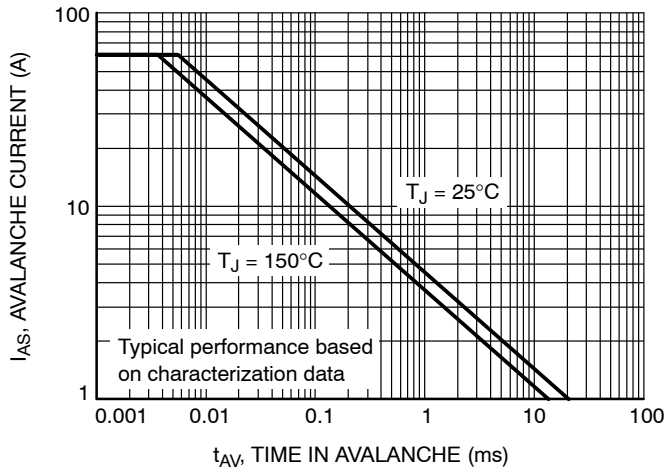
Figure 9. Unclamped Inductive Switching Capability
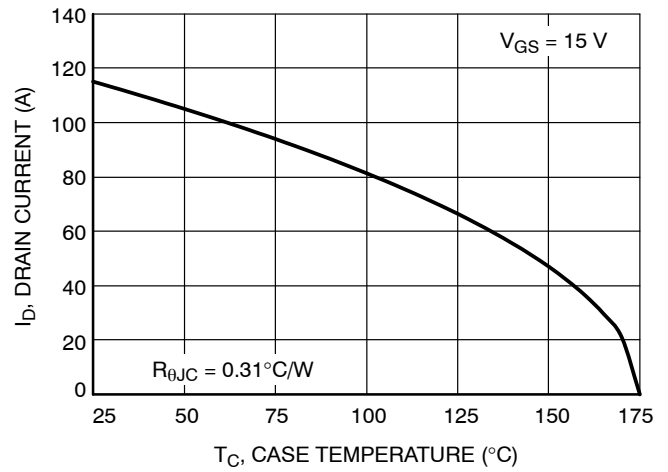
Figure 10. Maximum Continuous Drain Current vs. Case Temperature
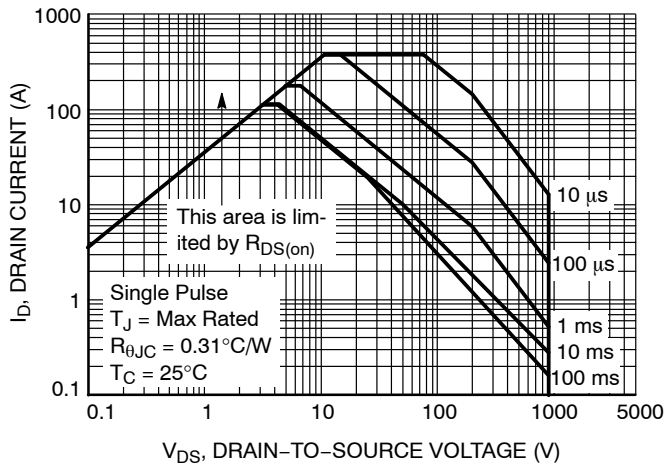
Figure 11. Safe Operating Area
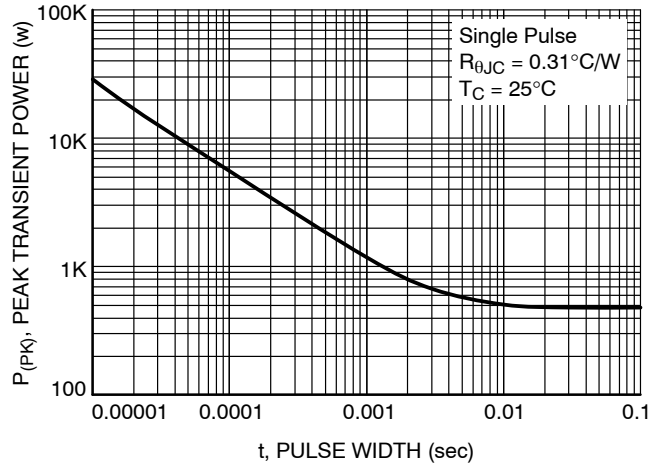
Figure 12. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS
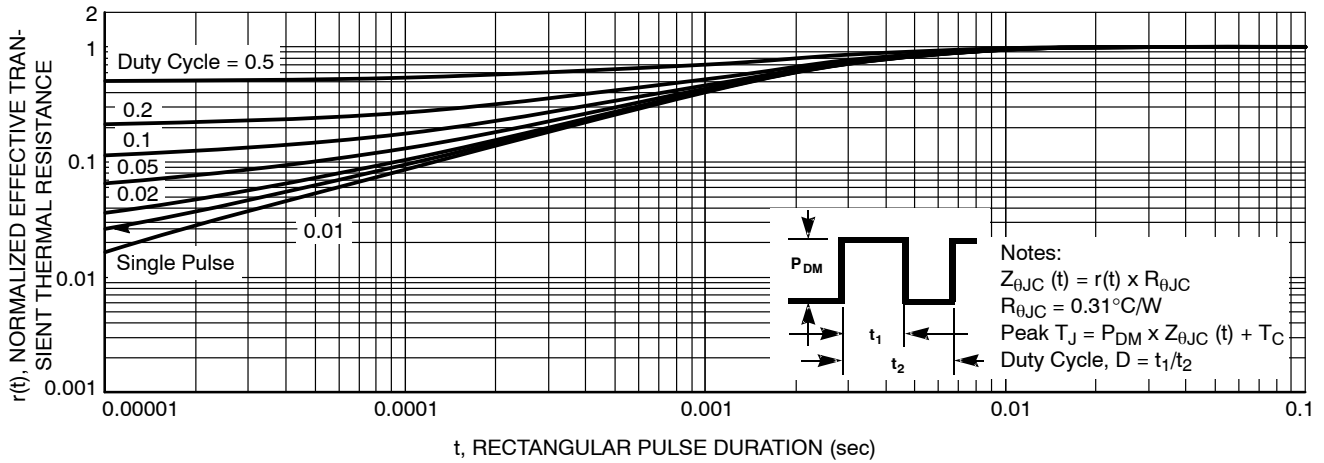
Figure 13. Junction−to−Ambient Transient Thermal Response Curve

Notes:
$Z_{\theta JC}(t) = r(t) \times R_{\theta JC}$
$R_{\theta JC} = 0.31°C/W$
Peak $T_J = P_{DM} \times Z_{\theta JC}(t) + T_C$
Duty Cycle, $D = t_1/t_2$

DEVICE ORDERING INFORMATION

Device	Package	Shipping[†]
NVBG020N090SC1	D2PAK−7L	800 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

D²PAK7 (TO−263−7L HV)
CASE 418BJ
ISSUE B

DATE 16 AUG 2019
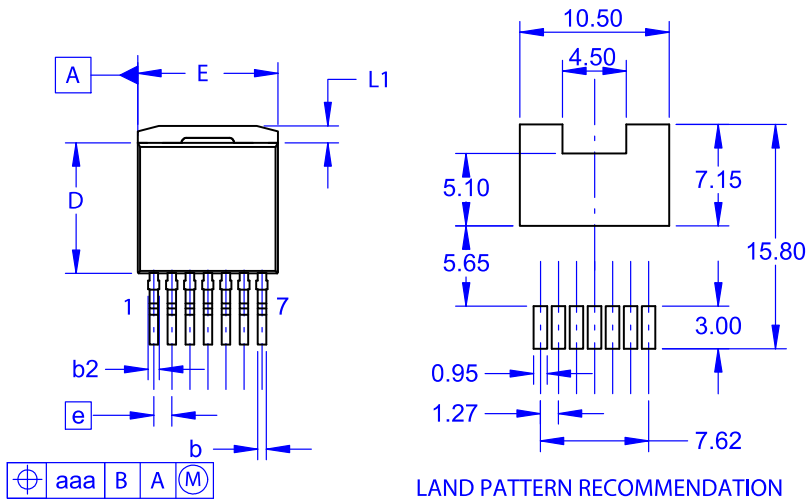
NOTES:
A. PACKAGE CONFORMS TO JEDEC TO-263
   VARIATION CB EXCEPT WHERE NOTED.
B. ALL DIMENSIONS ARE IN MILLIMETERS.
C. OUT OF JEDEC STANDARD VALUE.
D. DIMENSION AND TOLERANCE AS PER ASME
   Y14.5-2009.
E. DIMENSIONS ARE EXCLUSIVE OF BURRS,
   MOLD FLASH AND TIE BAR PROTRUSIONS.

LAND PATTERN RECOMMENDATION

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.30	4.50	4.70
A1	0.00	0.10	0.20
b2	0.60	0.70	0.80
b	0.51	0.60	0.70
c	0.40	0.50	0.60
c2	1.20	1.30	1.40
D	9.00	9.20	9.40
D1	6.15	6.80	7.15
E	9.70	9.90	10.20
E1	7.15	7.65	8.15
e	~	1.27	~
H	15.10	15.40	15.70
L	2.44	2.64	2.84
L1	1.00	1.20	1.40
L3	~	0.25	~
aaa	~	~	0.25
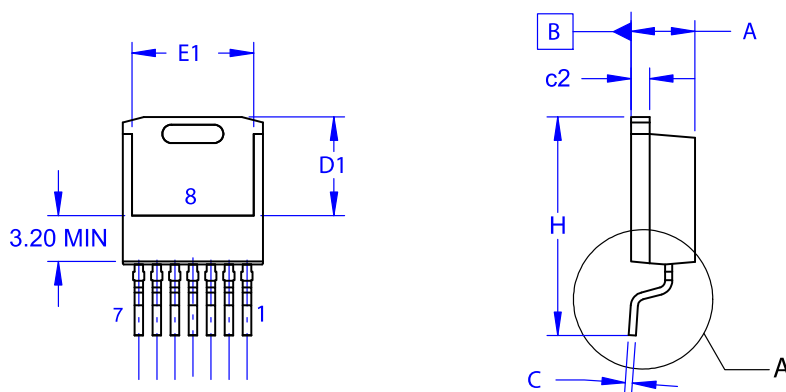
GENERIC MARKING DIAGRAM*
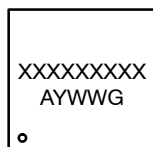
XXXXXXXXX
AYWWG

XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to
device data sheet for actual part marking.
Pb−Free indicator, "G" or microdot "▪", may
or may not be present. Some products may
not follow the Generic Marking.

DETAIL A
SCALE 2:1

SEATING PLANE

GAUGE PLANE

0°- 8°

R0.50
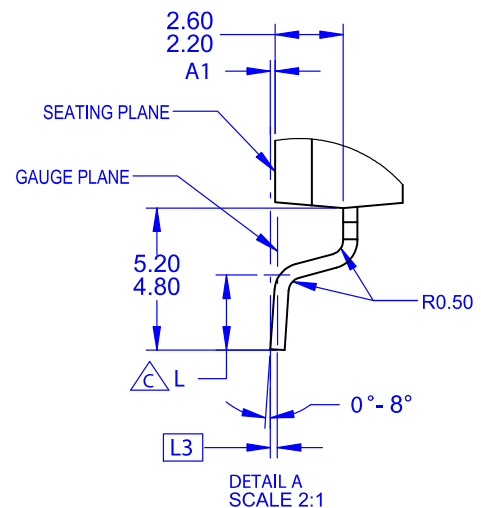
DOCUMENT NUMBER:	98AON84234G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	**D²PAK7 (TO−263−7L HV)**		PAGE 1 OF 1

PUBLICATION ORDERING INFORMATION

◊

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